SFH 4776

SYNIOS® P2720

IR Broadband Emitter - 120°





Applications

- Infrared Spectroscopy

Features:

- Package: clear silicone
- Corrosion Robustness Class: 3B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- Spectral range of emission: (typ) 650 ... 1050 nm
- Wide viewing angle of 120°
- Small outline dimensions
- Low thermal resistance (Max. 9 K/W)

Ordering Information

Туре	Total radiant flux ¹⁾ typ. $I_F = 350 \text{ mA}$; $\lambda = 600 \text{nm} - 1050 \text{nm}$; $t_p = 20 \text{ms}$ Φ_e	Ordering Code
SFH 4776	24 mW	Q65112A4886



Maximum Ratings

 $T_A = 25$ °C

Parameter	Symbol		Values
Operating temperature	T _{op}	min.	-40 °C
	ор	max.	85 °C
Storage temperature	T _{stg}	min.	-40 °C
	Sig	max.	85 °C
Junction temperature	T _j	max.	125 °C
Forward current	I _F	max.	500 mA
Surge current	I _{FSM}	max.	1 A
$t_p \le 2 \text{ ms}; D = 0.005$	1 0141		
Reverse current ²⁾	I _R	max.	200 mA
Power consumption	P _{tot}	max.	1900 mW
ESD withstand voltage	V _{ESD}	max.	2 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	200		

For the forward current and power consumption please see "maximum permissible forward current" diagram



Characteristics

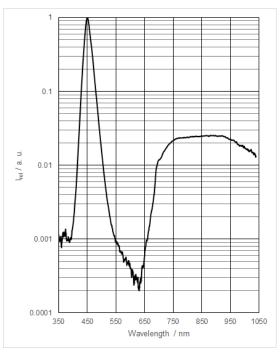
 $I_{_{\rm F}}$ = 350 mA; $t_{_{
m D}}$ = 20 ms; $T_{_{
m A}}$ = 25 °C

Parameter	Symbol		Values
Half angle	φ	typ.	60 °
Forward voltage 3)	V_{F}	typ. max.	2.95 V 3.5 V
Forward voltage $^{3)}$ I _F = 500 mA; t _p = 100 µs	V_{F}	typ. max.	3 V 3.8 V
Reverse voltage ²⁾ I _R = 20 mA	V_R	max.	1.2 V
Reverse voltage (ESD device) 2)	V _{R ESD}	min.	45 V
Radiant intensity $^{4)}$ $\lambda = 350 - 600 \text{ nm}$	l _e	typ.	29 mW/sr
Radiant intensity $^{4)}$ $\lambda = 600 - 1050 \text{ nm}$	l _e	typ.	8 mW/sr
Total radiant flux $^{1)}$ $\lambda = 350 - 600 \text{ nm}$	Фе	typ.	90 mW
Total radiant flux $^{1)}$ λ = 600 - 1050 nm	Фе	typ.	24 mW
Spectral flux λ = 750 nm	$\Phi_{e,\lambda}$	typ.	70 μW/nm
Spectral flux λ = 850 nm	$\Phi_{e, \lambda}$	typ.	75 μW/nm
Spectral flux λ = 950 nm	$\Phi_{e, \lambda}$	typ.	60 μW/nm
Thermal resistance junction solder point real 5)	$R_{ ext{thJS real}}$	max.	9.0 K / W



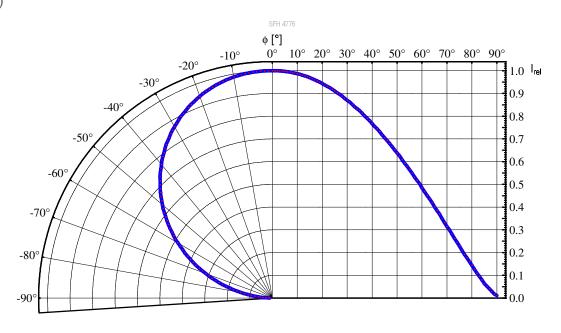
Relative Spectral Emission 6), 7)

 $I_{e,rel} = f(\lambda); I_F = 350 \text{ mA}; t_p = 10 \text{ ms}$



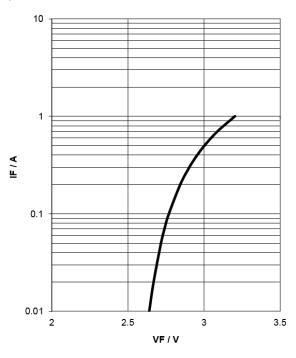
Radiation Characteristics 6), 7)

 $I_{e,rel} = f(\phi)$



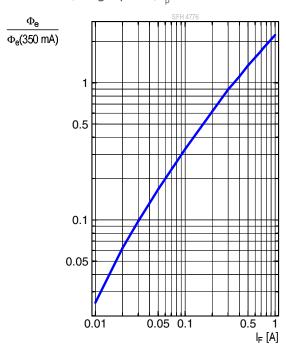
Forward current 6), 7)

 $I_F = f(V_F)$; single pulse; $t_p = 100 \mu s$



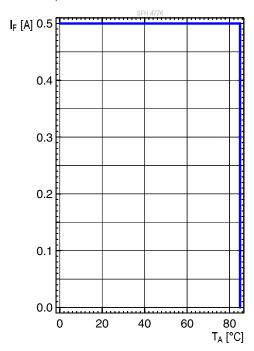
Relative Total Radiant Flux 6), 7)

 $\Phi_{\rm e}/\Phi_{\rm e}(350{\rm mA})$ = f (I_F); λ = 600 nm – 1050 nm; single pulse; t_p = 10 ms



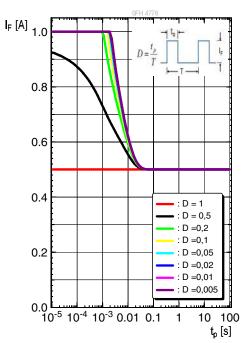
Max. Permissible Forward Current

 $I_{F,max} = f(T_S)$; Rth_{js} = 9K / W; single pulse



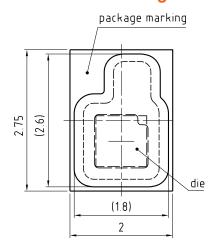
Permissible Pulse Handling Capability

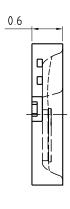
 $I_F = f(t_p)$; D = parameter; $T_S = 85$ °C

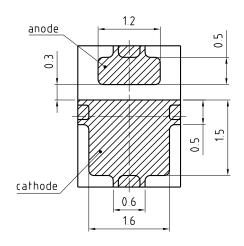




Dimensional Drawing 8)







General tolerance ±0.1

Lead finish Au

C67062-A0116-A11-04

Further Information:

Approximate Weight: 12.0 mg

Package marking: Cathode

Corrosion test: Class: 3B

Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC

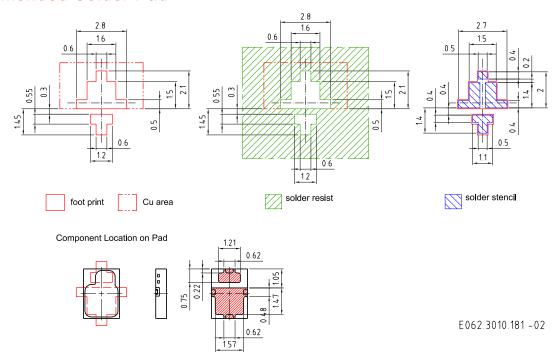
60068-2-43)

ESD advice: The device is protected by ESD device which is connected in parallel to the

Chip.



Recommended Solder Pad 8)

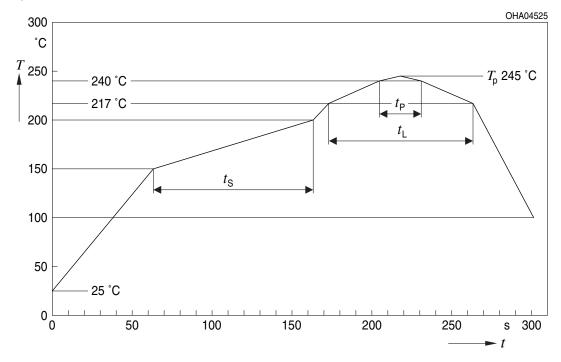


Dimensions in mm (inch).



Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



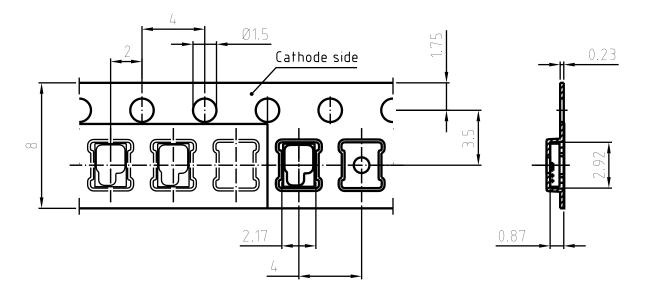
Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t_S T_{Smin} to T_{Smax}	t _s	60	100	120	S
Ramp-up rate to peak*) T_{Smax} to T_{P}			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t _L		80	100	S
Peak temperature	T _P		245	260	°C
Time within 5 °C of the specified peak temperature T _P - 5 K	t _P	10	20	30	S
Ramp-down rate* T _P to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

All temperatures refer to the center of the package, measured on the top of the component



^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

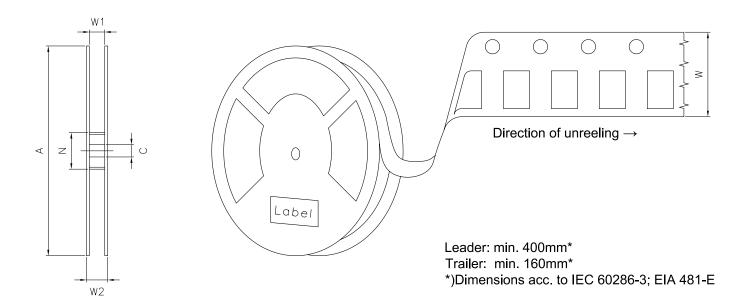
Taping 8)



C67062-A0116-B9-04



Tape and Reel 9)



Reel Dimensions

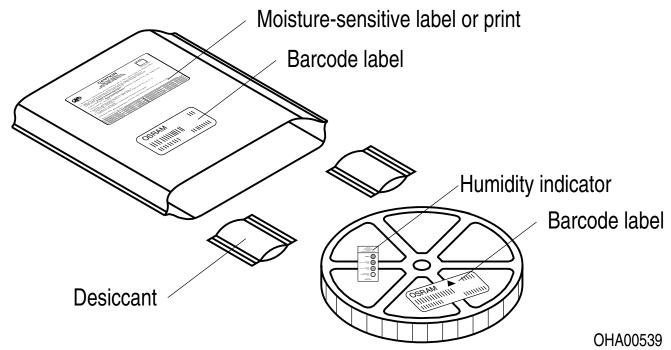
Α	W	N_{\min}	W_1	$W_{2 max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	2000



Barcode-Product-Label (BPL)



Dry Packing Process and Materials 8)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **moderate risk (exposure time 0.25 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



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Glossary

- Total radiant flux: Measured with integrating sphere.
- Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- Forward Voltage: The forward voltages are measured with a tolerance of ±0.1 V.
- ⁴⁾ **Radiant intensity:** Measured at a solid angle of Ω = 0.01 sr
- Thermal resistance: junction soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- ⁷⁾ **Testing temperature:** TA = 25°C (unless otherwise specified)
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- Tape and Reel: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



Revision History				
Version	Date	Change		
0.0	2018-12-11	Additional Information		
0.1	2020-08-26	Schematic Transportation Box Dimensions of Transportation Box		
0.2	2020-10-15	Discontinued		



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